

Docket No.: 55551 CIP (71360)

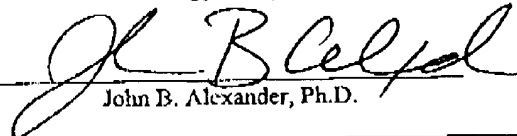
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: Kanayama, et al. EXAMINER: D. J. Buttner  
SERIAL NO.: 09/768,931 GROUP: 1712  
FILED: January 24, 2001  
FOR: THERMOPLASTIC RESIN COMPOSITION MOLDED PRODUCT  
AND USE

Honorable Commissioner of Patents and Trademarks  
Box: AF  
Washington, DC 20231

CERTIFICATE OF MAILING/TRANSMISSION (37 C.F.R. 1.8(A))

I hereby certify that this Letter (along with any paper referred to as being attached or enclosed) is being transmitted to the United States Postal Service by facsimile to Technology Group 1700 at 703 872 9311, on April 9, 2003.

  
John B. Alexander, Ph.D.

Dear Sir:

AMENDMENT AFTER FINAL PURSUANT TO 37 CFR § 1.116

Applicants are in receipt of the Office Action dated December 23, 2002 and request reconsideration of the above-identified application in view of the following amendments and remarks.